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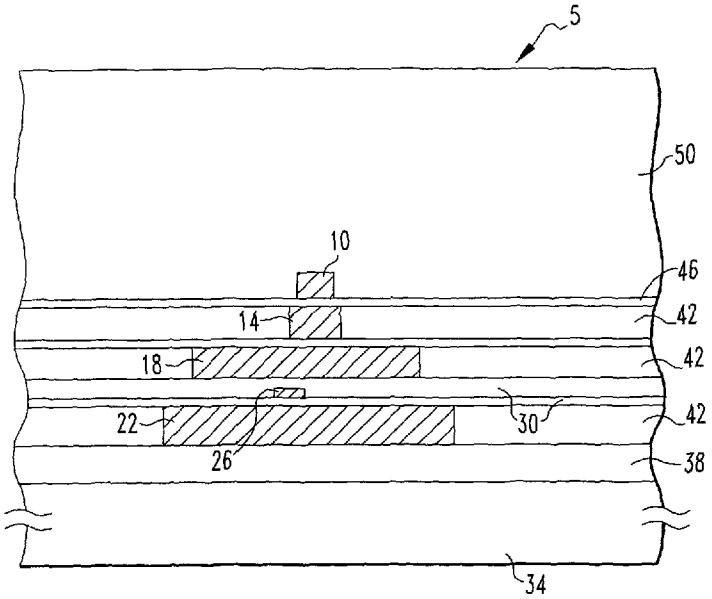
(54) Title: MATERIAL AND METHOD FOR IMPROVED HEAT DISSIPATION AND MECHANICAL HARDNESS FOR MAGNETIC RECORDING TRANSDUCERS AND OTHER ELECTRONIC DEVICES



(57) Abstract: The invention discloses a process for creating an improved surface that serves as a base or underlayer (38), planarization layer (42), read gap layer (30), write gap layer (46) and encapsulation material (50) for use in generic devices that require superior heat dissipation, mechanical hardness and surface smoothness. More particularly, the invention discloses an improved material, a polymer precursor to ceramic, for use in such devices, and methods for making magnetic recording transducers, semiconductors and microelectronic mechanical system transducers using this material.

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